

# The 4th International Conference on Engineering Physics, MEMS-Biosensors and Applications (4<sup>th</sup> ICEBA2023)

Host by: VNUHCM-University of Science (Vietnam)  
& Tohoku University (Japan)  
December 8&9, 2023

## CALL FOR PAPERS

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### Deadline

- Abstract submission and registration:

**October 30<sup>th</sup>, 2023**

- Full paper submission for presentation:

**November 15<sup>th</sup>, 2023**

- Conference payment fee: **Before**

**November 15<sup>th</sup>, 2023**

- Session schedule announcement:

**November 20<sup>th</sup>, 2023**

- Conference day: **December 8&9<sup>th</sup>, 2023**

- Full paper submission for

publication: **December 30<sup>th</sup>, 2023**

### Contact

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[phys.hcmus.edu.vn/ICEBA2023/#/](http://phys.hcmus.edu.vn/ICEBA2023/#/)

The purpose of the 4<sup>th</sup> ICEBA2023 is to link the researchers, scientists from Vietnam, Australia and Asian countries in the field of Engineering Physics and microelectronics and semiconductors for their applications in biomedical engineering, health sciences, hi-tech agriculture and smart cities. Besides, we also contribute to promoting international cooperation activities on joint research projects and international co-publications.

**The subject areas:** Contributed papers must be the new research works and are solicited in the following subject areas (but not limited to):

- *Applied Physics, Engineering Physics, Electronic Engineering and Nuclear Engineering;*

- *MEMS (MicroElectronMechanical System), Sensors, Biosensors and semiconducting devices;*

- *Microelectronics, IC design, low consumption devices, Renewable Energy*

- *Computing Science, Simulations and Modeling;*

- *Embedded systems, Internet of Things, Machine Learning, Artificial Intelligence,..*

- *Biomedical Engineering, Digital Microfluidics and their applications;*

Please submit your registration and abstract (around 200 words) via website or [4iceba2023@gmail.com](mailto:4iceba2023@gmail.com) before **October 30<sup>th</sup>, 2023**.

Full paper for peer-review process for presentation (as template) must be submit before **November 15<sup>th</sup>, 2023**.

**Publications:** The selected papers (from 4 to 8 pages) will be reviewed or recommended for the publications in one of the below Scopus/SCIE/Scimago database Journal *with your submission and payment* such as:

(1) *IEEE Transactions on Electrical and Electronic Engineering (Q3);*

(2) *IEEE Transactions on Sensors and Micromachines (Q4) ;*

(3) *Applied Sciences (MDPI, Q1/Q2);*

(4) *Special Issue of Nanomaterials (MDPI, Q1)*

**Host:** VNUHCM-University of Science and Tohoku University (Japan).

**Technical Supports:** IEEE Vietnam Section, Institute Electrical Engineer of Japan (IEEJ), Institute of Korean Electrical & Electronic Engineers (IKEEE) and HoChiMinh Semiconducting Industrial Association (HSIA).

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